

## Patent Abstracts of Japan

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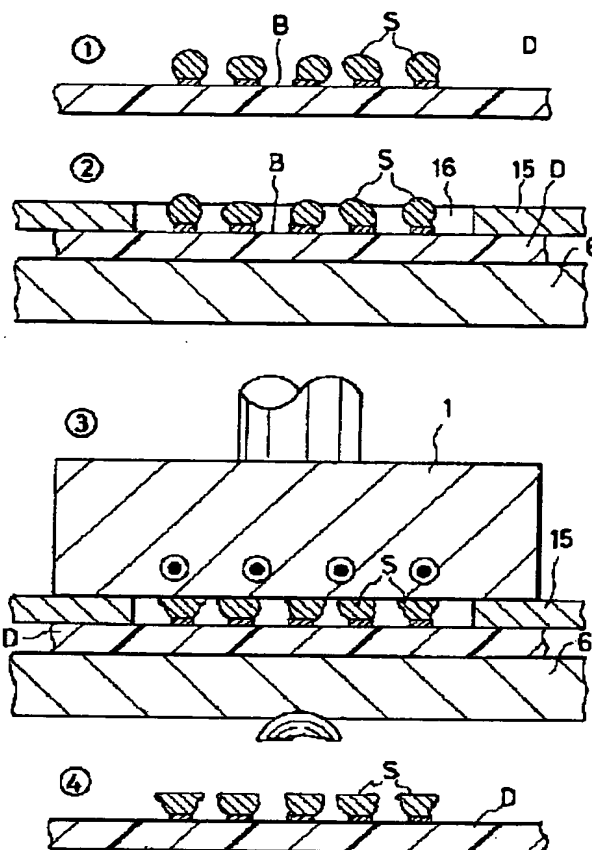
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TITLE : METHOD OF FLATTENING SOLDER BUMP AND ITS DEVICE



**ABSTRACT :** PROBLEM TO BE SOLVED: To flatten uneven solder bumps by pressing the solder bumps, keeping the distance from the section other than the solder bump formation place of a multifunction device to the pressing face of a press body at a specified interval, after depositing the solder to the solder bump formation place of the multifunction place, thereby forming the solder bumps.

**SOLUTION:** Solder bumps S are made by depositing solder to the solder bump formation place B of a multifunction device D. Next, a multifunction device D is put in the specified position on a balancing stage 6, and a spacer 15 is placed, being arranged so that an opening 16 may be in the position of a solder bump formation place. Then, the solder bumps S are pressed with a press body 1. At this time, the press body 1 is arranged to perform the pressing until it contacts the spacer 15. Hereby, even if the board of the multifunction device D is unequal, all the solders S of the multifunction device D can be equalized in height to the section other than the solder bump formation places B of the multifunction device D.

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